

SPECIFICATIONS CL28GT3C5MA

OUTLINES DIMENSIONS

DESCRIPTION

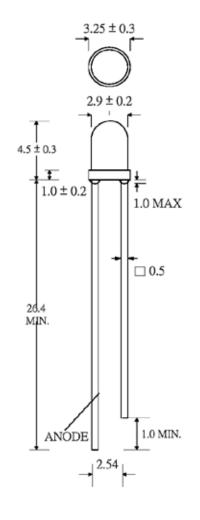
- Super bright LED lamp
- Round type
- T1 (3mm) diameter
- Lens color: Water clear
- With flange
- Solder leads without stand-off



- Emitted color: Super Green
- High luminous intensity
- Technology: InGaN
- Peak wavelength λ_p = 528nm
- Viewing angle: 30°



- 1. All Dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CL28GT3C5MA	InGaN	Green	Water Clear	30°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	Pb	120	mW			
Pulse Current Forward Current	lFP	100	mA			
Continuous Forward Current	lF	30	mA			
Reverse Voltage	VR	5	V			
Operating Temperature Range	Topr	-40~+85	°C			
Storage Temperature Range	Тѕтс	-40~+100	°C			
IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

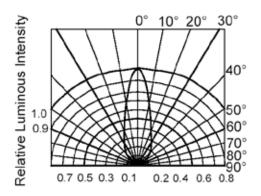
(TA=25°C)

Darameter	Symbol	Test Condition	Value			l lait
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	I⊧ = 5mA	2000	3000	-	mcd
Forward Voltage	VF	I _F = 5mA	-	2.9	3.5	V
Reverse Leakage Current	lR	V _R = 5V	-	-	10	μΑ
Viewing Angle	201/2	I _F = 5mA	-	30	-	deg
Peak Wavelength	λР	I⊧ = 5mA	-	520	-	nm
Dominant Wavelength	λD	I⊧ = 5mA	-	525	-	nm

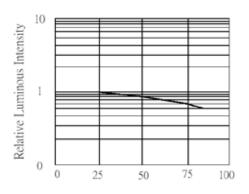
^{*}Tolerance of viewing angle: -10 / +5 deg.



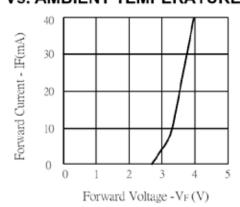
OPTICAL CHARACTERISTIC CURVES



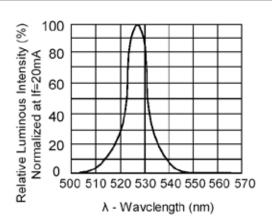
RADIATION DIAGRAM



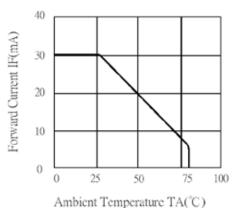
LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



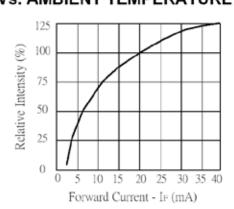
FORWARD CURRENT Vs. FORWARD VOLTAGE



RELATIVE LUMINOUS INTENSITY Vs. WAVELENGTH



FORWARD CURRENT Vs. AMBIENT TEMPERATURE



LUMINOUS INTENSITY Vs. FORWARD CURRENT





SOLDERING CONDITIONS – LAMP TYPE LED

SOLDERING PROFILE

1. Iron:

Soldering Iron: 30W max Temperature 350 °C max

Soldering Time: 3 seconds max (one time)
Distance: 2mm min (from solder joint to body)

2. Wave Soldering Profile:

Dip soldering

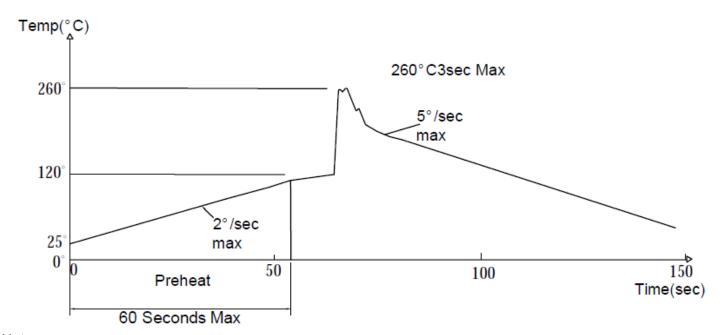
Preheat: 120 °C max

Preheat time: 120 seconds max

2 °C/sec (max)

Ramp-down: -5 °C/sec (max) Solder bath: 260 °C max Dipping time: 3 seconds max

Distance: 2mm min (from solder joint to body)



Notes:

- 1. Wave solder should not be made more than one time.
- 2. Only select one of the soldering conditions as above.

